

MS-6507E

Version 1.0
03/19/2002 Update

INTEL (R) Brookdale-E Chipset
Willamette/Northwood 478pin mPGA-B Processor Schematics

CPU:
Willamette/Northwood mPGA-478B Processor

System Brookdale-E Chipset:

**INTEL MCH (North Bridge) +
INTEL ICH4 (South Bridge)**

On Board Chipset:

BIOS -- FWH

LPC Super I/O -- W83627HF

Clock Generator -- CY28349

AC'97 Codec -- AvanceLogic AC201A/AC202A

Onboard Lan Chipset-- RealTek RTL8101L

Expansion Slots:

AGP2.0 SLOT * 1

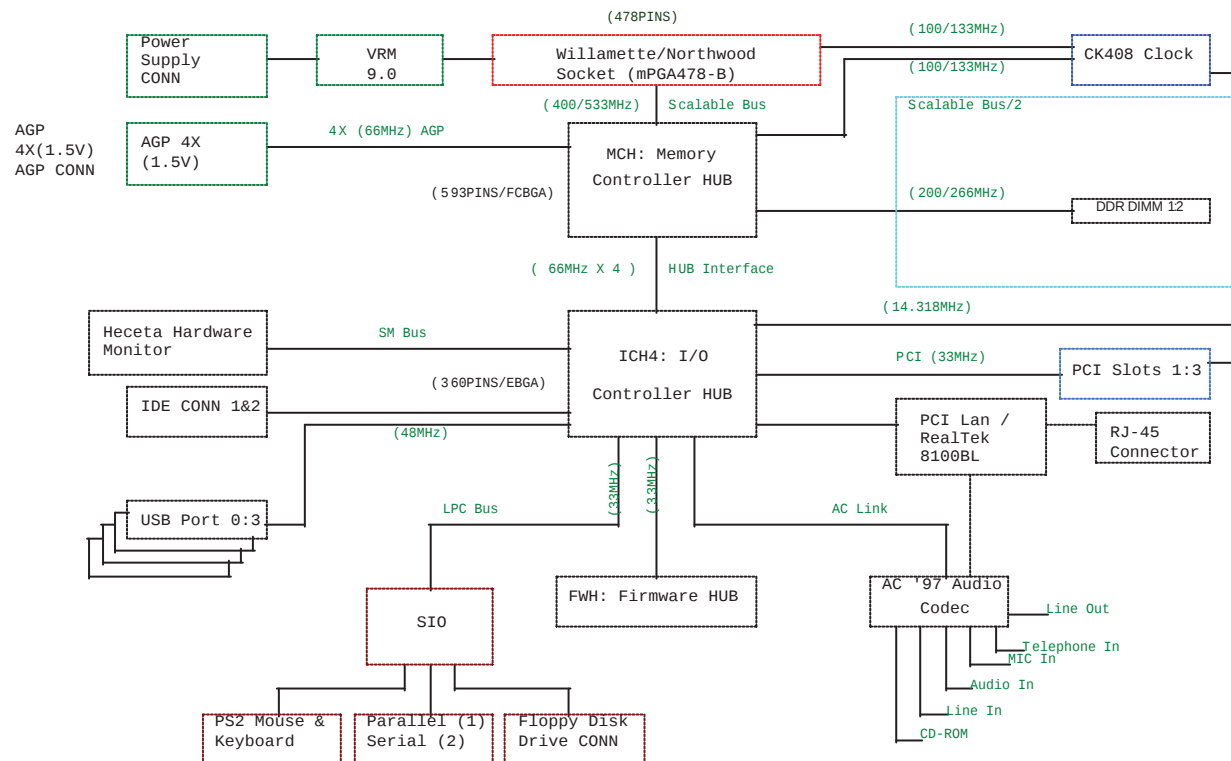
PCI2.2 SLOT * 3 (PCI Slot 3 for Medion Option)

CNR1.2 SLOT * 1

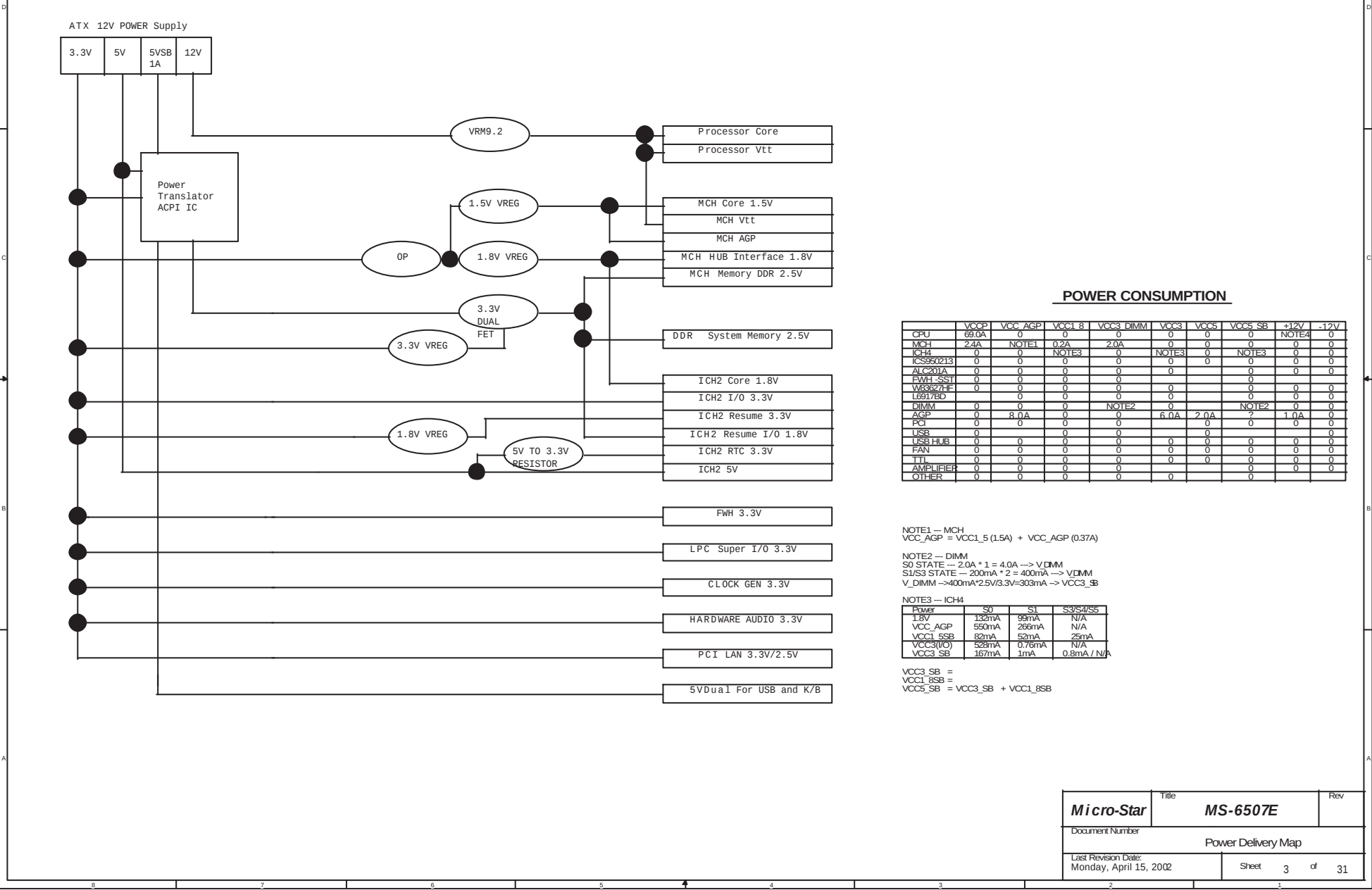
ERP BOM	Function Description	
601-6507E-01S	MS-6507E 100	With LAN.
601-6507E-020	MST Option: I	MST Standard
601-6507E-02S	MS-6507E 100	Without LAN.
601-6507E-010	MST Standard	MST Standard
601-6507E-XXX		Medion SPEC.
	For Actebis:	With CNR, STR. W/O ISA, LAN. I/O with Shield.

Cover Sheet	1
Block Diagram	2
Power Delivery Map	3
GPIO Spec.	4
Clock ICS950213AF & ATA100 IDE CONNECTORS	5
mPGA478-B INTEL CPU Sockets	6 - 7
INTEL Brookdale-E MCH -- North Bridge	8 - 9
DDR DIMMM1,2	10
DDR Damping & DDR Termination	11
INTEL ICH4 -- South Bridge	12-13
Ac'97 Codec and Audio Connector & Game Port	14
AGP 4X SLOT (1.5V)	15
PCI SLOT 1 & 2 & 3	16
Realtek RTL8101L LAN	17
LPC I/O W83627HF	18
FWH & CNR Connector	19
USB & FAN Connectors	20
Front Panel & Connectors	21
ACPI Controller	22
L6719B CPU Power (PWM)-VRM9.0	23
IO Connectors	24
JUMPER SETTING	25
History I	26
LAYOUT GUIDE	27-31

Micro-Star	Title MS-6507E	Rev 1.0
Document Number	Cover Sheet	
Last Revision Date: Monday, April 15, 2002	Sheet 1 of 31	



Power Delivery Map



General Purpose I/O Spec.

ICH4		
GPIO Pin	Type	Function
GPIO 0	I	REQ#A
GPIO 1	I	REQ#5
GPIO 2	I	IRQE#
GPIO 3	I	IRQF#
GPIO 4	I	IRQG#
GPIO 5	I	IRQH#
GPIO 6~7	I	Not Implemented
GPIO 8	I	SIO PME#
GPIO 9~10	I	Not Implemented
GPIO 11	I	External SMI
GPIO 12~13	I	Not Implemented
GPIO 14~15	I	Not Implemented
GPIO 16	O	Non Connect
GPIO 17	O	GNT#5
GPIO 18~21	O	Non Connect
GPIO 22	O/D	Non Connect
GPIO 23	O	BIOS Protect
GPIO 24~27	I/O	Non Connect
GPIO 28	I/O	LAN DISABLED (ICH4)
GPIO 29~47	I/O	Non Connect

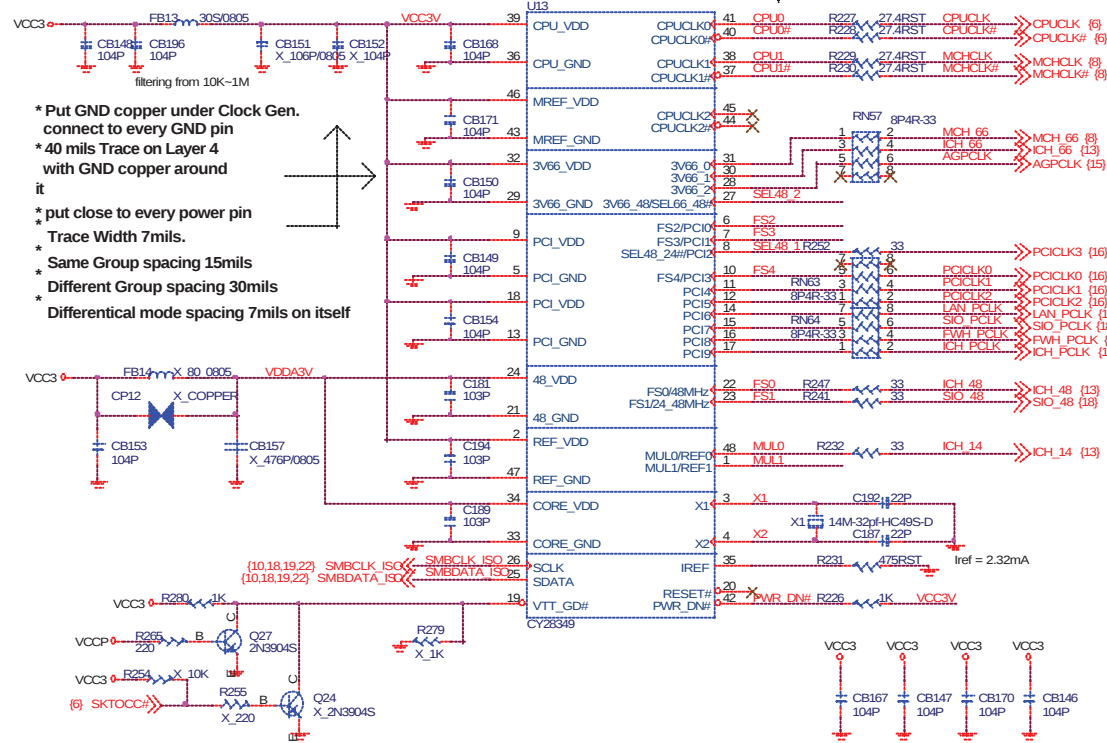
FWH

GPIO Pin	Type	Function
GPI 0	I	ATA IDE 1 Detect
GPI 1	I	ATA IDE 2 Detect
GPI 2	I	Reserved
GPI 3	I	Reserved

DEVICE	ICH INT Pin	IDSEL	CLOCK
PCI Slot 1	INTA# INTB# INTC# INTD#	AD16	PCICLK0
PCI Slot 2	INTB# INTC# INTD# INTA#	AD17	PCICLK1
PCI Slot 3	INTC# INTD# INTA# INTB#	AD18	PCICLK2
PCI Slot 3	INTG#	AD19	PCICLK3
PCI Lan	INTD# / INTF#	AD29	LANPCLK

CLOCK GENERATOR BLOCK

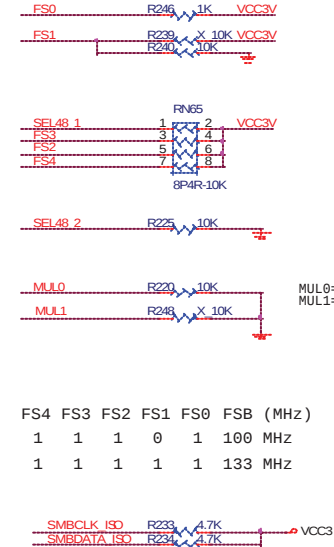
*Trace < 0.5"



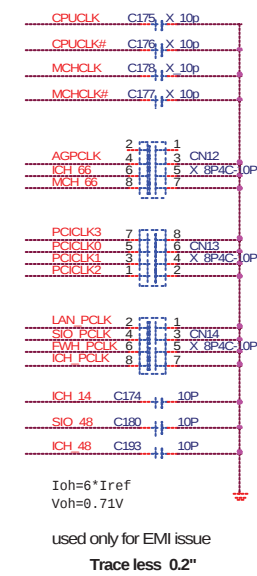
Shut Source Termination Resistors



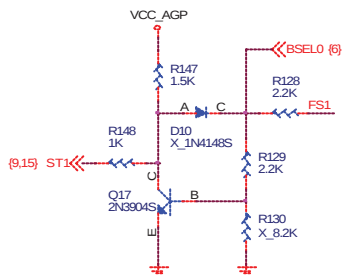
CLOCK STRAPPING RESISTORS



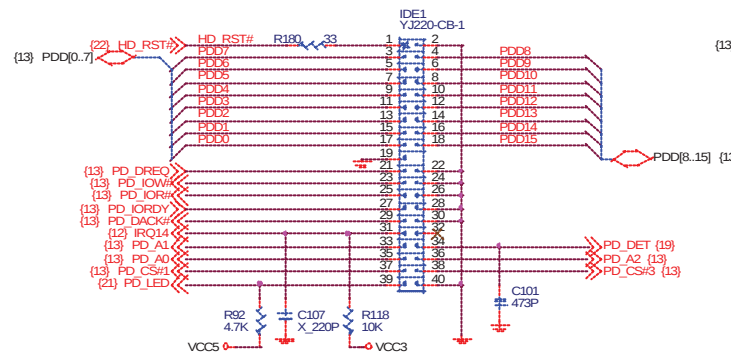
Pull-Down Capacitors



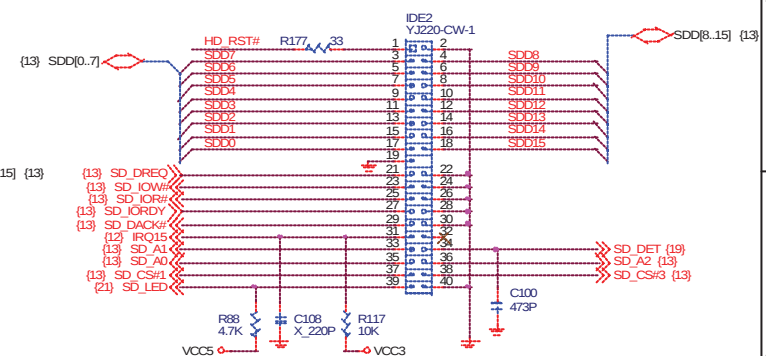
FS4	FS3	FS2	FS1	FS0	CPU (MHz)
1	1	1	0	1	100 MHz
1	1	1	1	1	133 MHz



PRIMARY IDE BLOCK



SECONDARY IDE BLOCK



ATA100 IDE CONNECTORS

- * Trace Width : 5mils
- * Trace Spacing : 7mils
- * Length(longest)-Length(shortest)<0.5"
- * Trace Length less than 5"

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Title Clock Gen & ATA100 IDE Connectors			
Size	Document Number	MS-6507E	
Date	Monday, April 15, 2002	Sheet	5 of 31

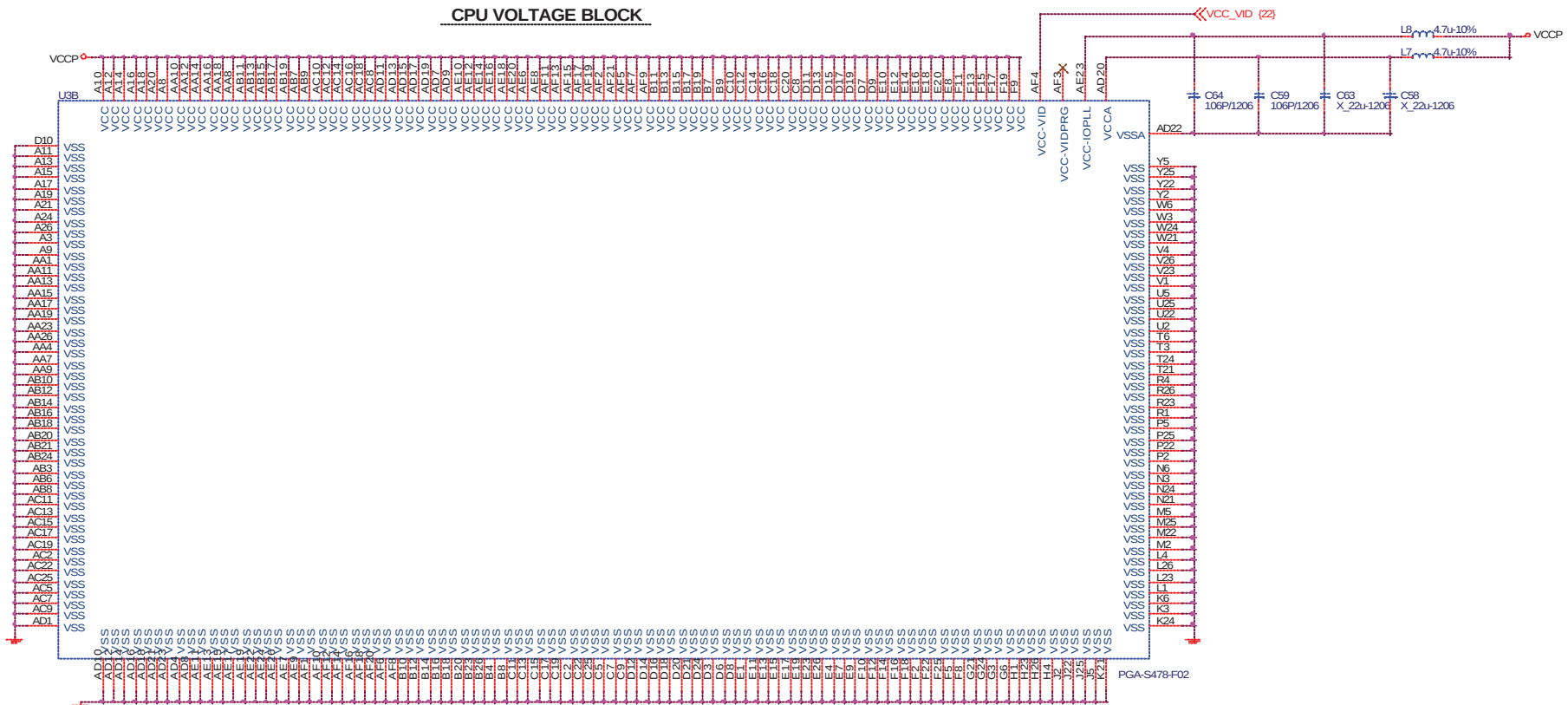
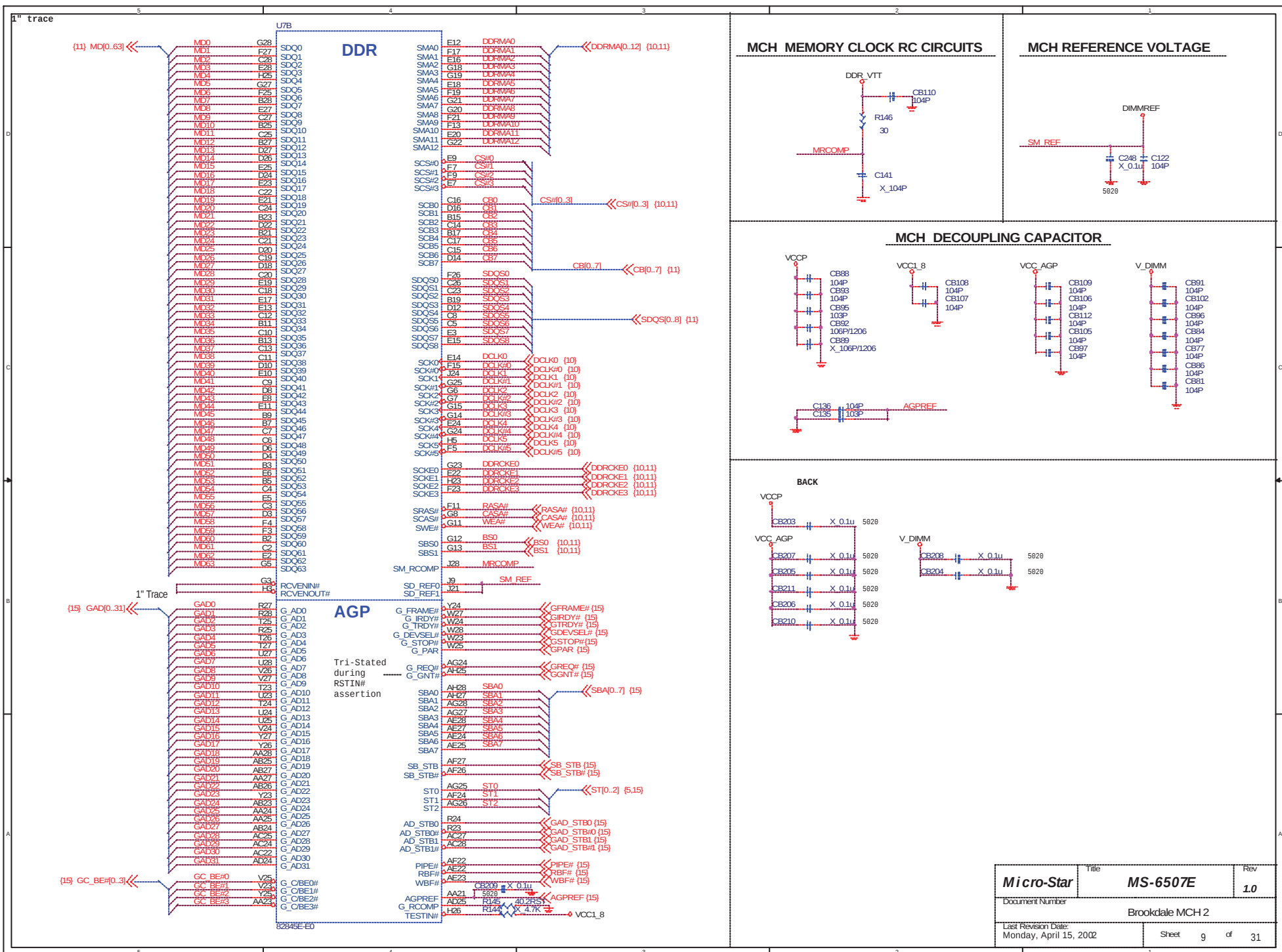
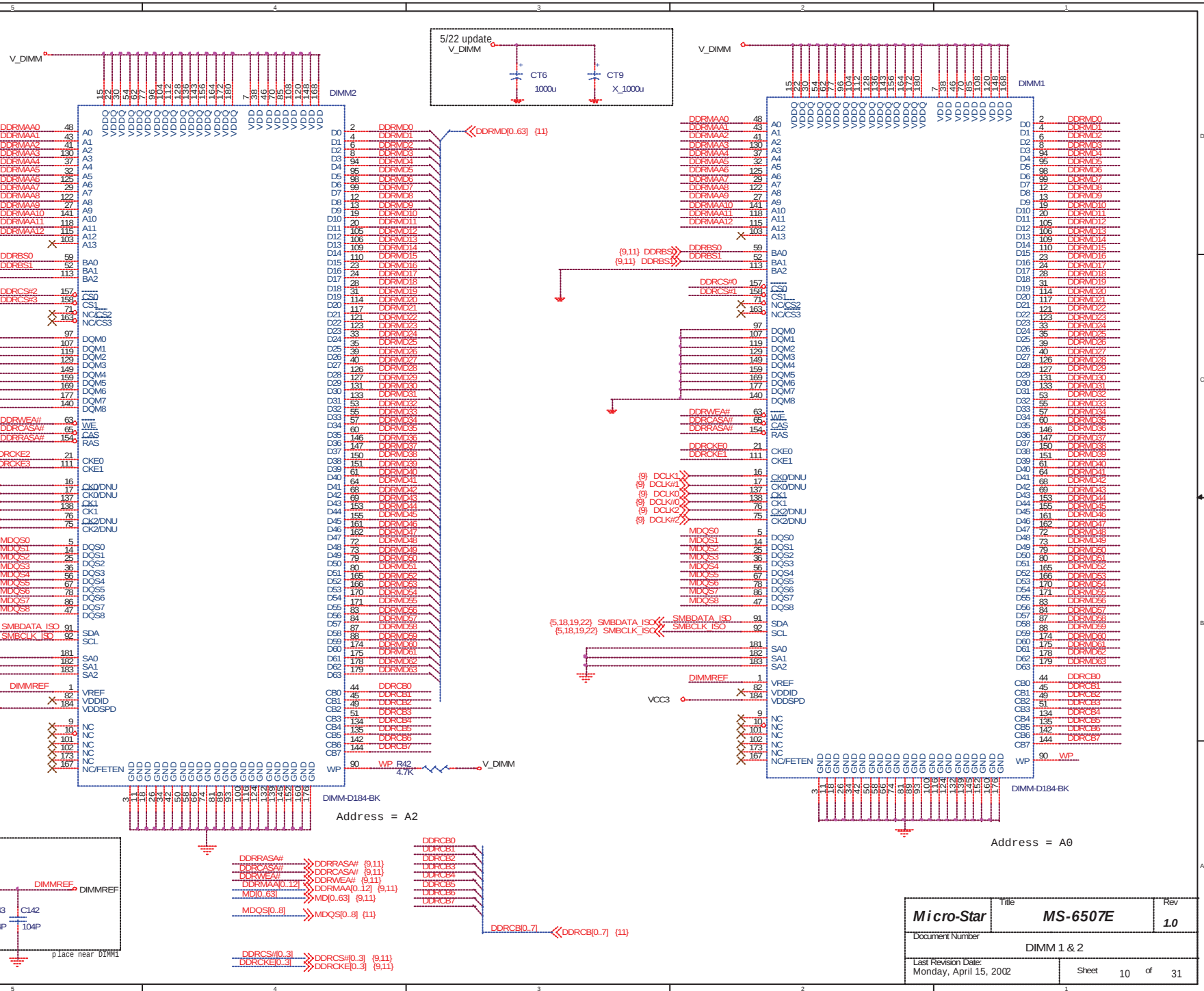


Figure 10 shows five circuit diagrams for capacitor placement on the CPU cavity. Each diagram illustrates a VCCP supply line connected to a series of capacitors. The capacitors are labeled with their values and part numbers.

- Diagram 1 (Left):** VCCP supply line connected to a series of capacitors: CB32 (106P/1206), CB31 (106P/1206), CB34 (106P/1206), and X_106P/1206. Below the diagram is the note: "PLACE CAPS WITHIN CPU CAVITY".
- Diagram 2:** VCCP supply line connected to a series of capacitors: CB35 (106P/1206), X_106P/1206, CB36 (106P/1206), CB20 (106P/1206), CB48 (106P/1206), X_106P/1206, CB18 (106P/1206), and X_106P/1206. Below the diagram is the note: "PLACE CAPS WITHIN CPU CAVITY".
- Diagram 3:** VCCP supply line connected to a series of capacitors: CB24 (106P/1206), X_106P/1206, CB33 (106P/1206), CB17 (106P/1206), X_106P/1206, CB41 (106P/1206), CB43 (106P/1206), CB34 (106P/1206), and X_106P/1206. Below the diagram is the note: "PLACE CAPS WITHIN CPU CAVITY".
- Diagram 4:** VCCP supply line connected to a series of capacitors: CB19 (106P/1206), X_106P/1206, CB38 (106P/1206), CB14 (106P/1206), X_106P/1206, CB32 (106P/1206), CB37 (106P/1206), CB29 (106P/1206), and X_106P/1206. Below the diagram is the note: "Reserve if necessary."
- Diagram 5 (Right):** VCCP supply line connected to a series of capacitors: CB44 (106P/1206), CB42 (106P/1206), X_106P/1206, CB15 (106P/1206), X_106P/1206, CB56 (106P/1206), X_106P/1206, CB21 (106P/1206), CB27 (106P/1206), CB22 (106P/1206), and X_106P/1206. Below the diagram is the note: "PLACE CAPS WITHIN CPU CAVITY SOLDER".

Micro-Star	Title	Rev
	MS-6507E	1.0
Document Number		
INTEL mPGA478-B CPU2		
Last Revision Date: Monday, April 15, 2002		Sheet 7 of 31





DDR DAMPING

The schematic shows the connection of DDR memory modules to the system bus. It includes the following components and connections:

- Memory Modules:** DDRMD0 through DDRMD63, connected to the system bus via address and data lines.
- Chipset:** Connected to the memory modules via address and data lines.
- DDR DIMM:** Connected to the memory modules via address and data lines.
- Termination:** 100Ω termination resistors are shown at the ends of the address and data lines.
- Command Signals:** DDRCS#0 through DDRCS#3, DDRCB#0 through DDRCB#3, and DDRCKE#0 through DDRCKE#3 are connected to the memory modules.
- Power and Ground:** DDR_VTT and GND are connected to the memory modules.

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Short by trace, resistors TBD

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DDR TERMINATION

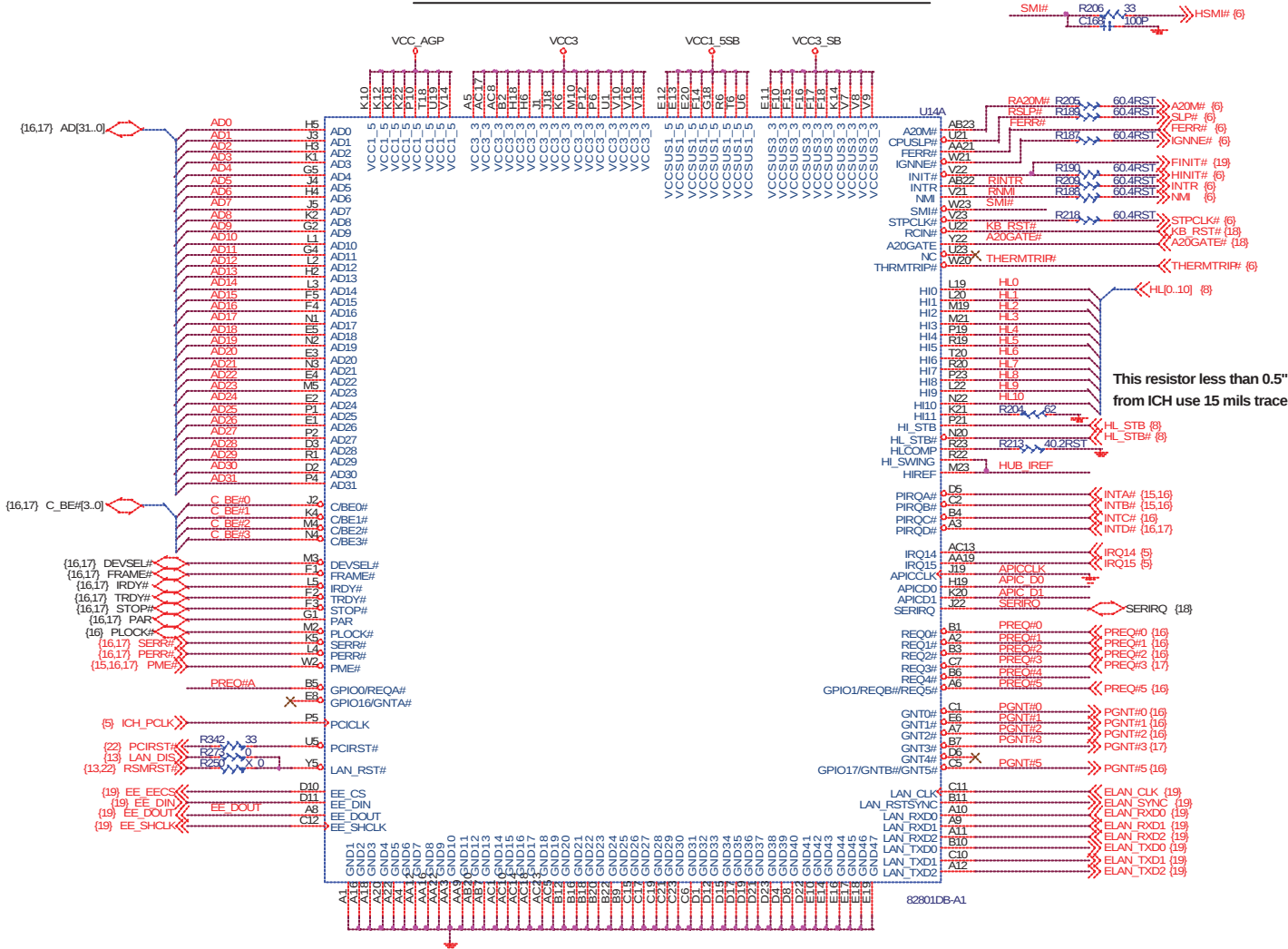
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Short by trace, resistors TBD

[illegible][illegible]

ICH4 PCI / HUB LINK / CPU / LAN / INTERRUPT SIGNALS

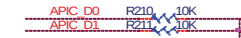
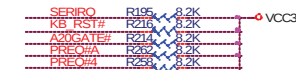


ICH4 STRAPPING RESISTORS

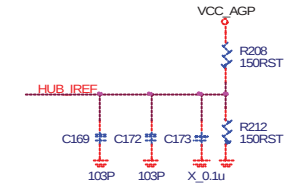


Reserved pull-down resistor for ICH4 reserved function straps.

ICH4 PULL-UP/DOWN RESISTORS

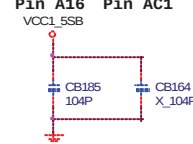
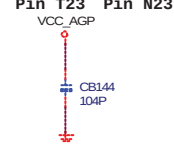
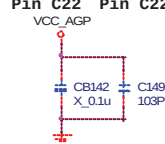
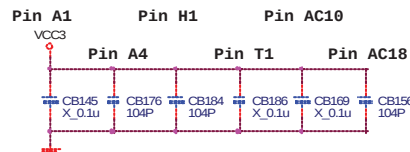


ICH4 REFERENCE VOLTAGE



Place Cap. as Close as possible to ICH4 < 0.25"
Trace width use 12 mils and 10mils space

ICH4 DECOUPLING CAPACITORS Place one 0.1u close to ICH4 <100 mil



FOR Core Logic

FOR PLL

FOR Hub Interface



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Title			ICH4 PCI & HI & LAN	
Size	Document Number	MS-6507E		Rev 1.0
Date:	Monday, April 15, 2002	Sheet	12	of 31

AUDIO CODE CRYSTAL CIRCUIT

The diagram illustrates an audio code crystal circuit. It consists of a central crystal, X3, with a frequency of 24.576MHZ. The crystal's pin 1 is connected to the XTALOUT line, and pin 2 is connected to the XTALIN line. A resistor, R331, with a value of 1M, is connected between XTALOUT and XTALIN. Two capacitors, C224 and C239, both with a value of 22P, are connected from XTALOUT and XTALIN respectively to ground.

DECOUPLING CAPACITOR

The diagram illustrates a decoupling capacitor network for a multi-layer PCB. It shows two signal traces, FB15 and CP7, each with a series capacitor (CP13 and CP7) and a shunt decoupling capacitor (C247 and C133) connected to ground. A separate VDD3 supply line has a shunt decoupling capacitor (CB197) connected to ground. The ground plane is indicated by red symbols at the bottom.

GAME/MIDI CONNECTOR

The diagram illustrates the internal wiring of a game controller's connector (J2A) to a MIDI interface. The connector is a 15-pin D-sub connector.

Game Controller Side (Left):

- Pin 1:** Connected to VCC5 via a 104pF capacitor (CB80).
- Pin 2:** Connected to JYS_P80 (18).
- Pin 3:** Connected to JYS_AX0 (18).
- Pin 4:** Connected to JYS_AX1 (18).
- Pin 5:** Connected to JYS_PB1 (18).
- Pin 6:** Connected to JYS_P83 (18).
- Pin 7:** Connected to JYS_AX2 (18).
- Pin 8:** Connected to JYS_OUT (18).
- Pin 9:** Connected to JYS_AX3 (18).
- Pin 10:** Connected to JYS_P82 (18).
- Pin 11:** Connected to JYS_PB2 (18).
- Pin 12:** Connected to JYS_PB1 (18).
- Pin 13:** Connected to JYS_P83 (18).
- Pin 14:** Connected to JYS_AX2 (18).
- Pin 15:** Connected to JYS_OUT (18).

MIDI Interface Side (Right):

- Pin 1:** Connected to JYS_P83 (18).
- Pin 2:** Connected to JYS_AX2 (18).
- Pin 3:** Connected to JYS_OUT (18).
- Pin 4:** Connected to JYS_AX3 (18).
- Pin 5:** Connected to JYS_P82 (18).
- Pin 6:** Connected to JYS_PB2 (18).
- Pin 7:** Connected to JYS_PB1 (18).
- Pin 8:** Connected to JYS_P83 (18).
- Pin 9:** Connected to JYS_AX2 (18).
- Pin 10:** Connected to JYS_OUT (18).
- Pin 11:** Connected to JYS_AX3 (18).
- Pin 12:** Connected to JYS_P82 (18).
- Pin 13:** Connected to JYS_PB2 (18).
- Pin 14:** Connected to JYS_PB1 (18).
- Pin 15:** Connected to JYS_P83 (18).

Connector (J2A):

- Pin 1:** Connected to JYS_P80 (18).
- Pin 2:** Connected to JYS_AX0 (18).
- Pin 3:** Connected to JYS_AX1 (18).
- Pin 4:** Connected to JYS_PB1 (18).
- Pin 5:** Connected to JYS_P83 (18).
- Pin 6:** Connected to JYS_AX2 (18).
- Pin 7:** Connected to JYS_OUT (18).
- Pin 8:** Connected to JYS_AX3 (18).
- Pin 9:** Connected to JYS_P82 (18).
- Pin 10:** Connected to JYS_PB2 (18).
- Pin 11:** Connected to JYS_PB1 (18).
- Pin 12:** Connected to JYS_P83 (18).
- Pin 13:** Connected to JYS_AX2 (18).
- Pin 14:** Connected to JYS_OUT (18).
- Pin 15:** Connected to JYS_AX3 (18).

Other Components:

- Capacitors:** CB80 (104pF), CB101 (39pF), CB82 (104pF), C119 (100pF), C114 (100pF).
- Resistors:** R138 (2.2K), R126 (2.2K), R137 (2K), R139 (2K), R125 (2K), R126 (2K).
- Switches:** POLY SWITCH MICRO5MD110 FS2, R46 (8P4C-2.2K).

Intel Front Audio Connector

The diagram illustrates the electrical connections for the Intel Front Audio Connector. The central component is a multi-pin IC with the following connections:

- Pin 1 (MIC IN):** Connected to a +5VR supply through a 102pF capacitor (C243) and a 4.7k resistor (R336).
- Pin 2 (GND):** Ground connection.
- Pin 3 (MICPWR):** Microphone power supply connection.
- Pin 4 (VCC5):** Connected to a +5VR supply through a 104pF capacitor (C240).
- Pin 5 (FLINE OUTR):** Connected to the right speaker output (SPEAKER_R).
- Pin 6 (LINE NEXT R):** Line output connection.
- Pin 7 (HPON):** Headphone output connection.
- Pin 8 (FLINE OUTL):** Connected to the left speaker output (SPEAKER_L).
- Pin 9 (LINE NEXT L):** Line output connection.
- Pin 10 (LINE_OUTL):** Line output connection.

Additional components and connections include:

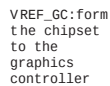
- Resistors:** R336 (4.7k) and R335 (4.7k).
- Capacitors:** C243 (102pF), C240 (104pF), C242 (102pF), and C241 (102pF).
- Connectors:** JAUD1, Y3205-IA, SSS1, and TTT1.
- Jumpers:** YJUMPER-MG and YJUMPER-MG.

Micro Star Restricted Secret

File	Rev
AC97 CODEC AD1885	1.0
Document Number	
MS-6507E	
MICRO-STAR INT'L CO.,LTD.	Last Revision Date:
No. 69, Li-De St, Jung-Ho City, Taipei Hsien, Taiwan	Monday, April 15, 2002
http://www.msi.com.tw	Sheet 14 of 31

Title	AC97 CODEC AD1885	Rev	
Document Number	MS-6507E		1.0
MICRO-STAR INT'L CO.,LTD. No. 69, Li-De St, Jung-He City, Taipei Hsien, Taiwan http://www.msi.com.tw		Last Revision Date:	
		Monday, April 15, 2002	
Sheet		14	of 31

VCC5 = 60mils trace / 15 mils space

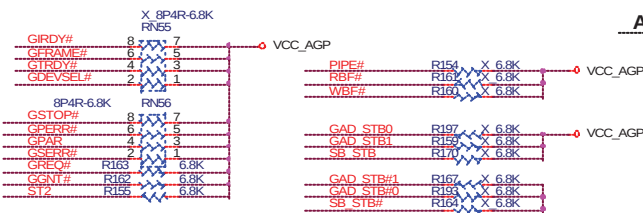


AGP Slot Imax
VCC AGP 8.0A
VCC3 6.0A
VCC12 1.0A
VCC5 2.0A

```
VREF_GC:form
the graphics
controller to
the chipset
```

VCC_AGP

Trace:Space=12mils:25mils

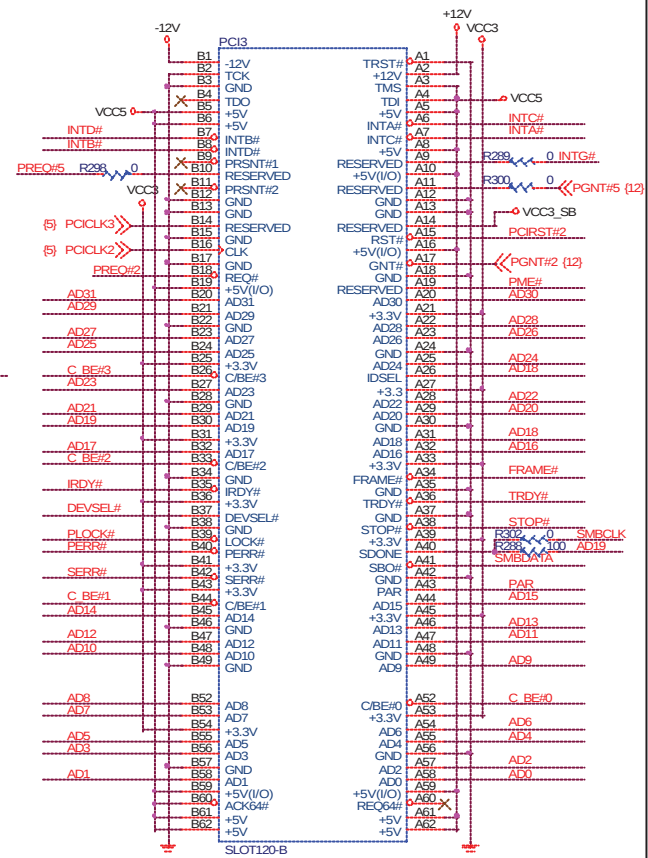


The circuit diagram shows a 10V DC voltage source connected in series with a 2K resistor and a 166 ohm resistor. The current flowing through the circuit is labeled as I .

Place these resistors between PCI and AGP slot

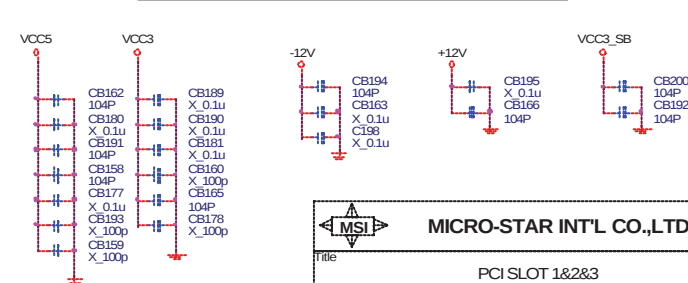
Micro-Star	Title	MS-6507E	Rev	1.0
Document Number		AGP Slot		
Last Revision Date: Monday, April 15, 2002		Sheet 15 of 31		

PCI SLOT 3 (PCI VER: 2.2 COMPLY)

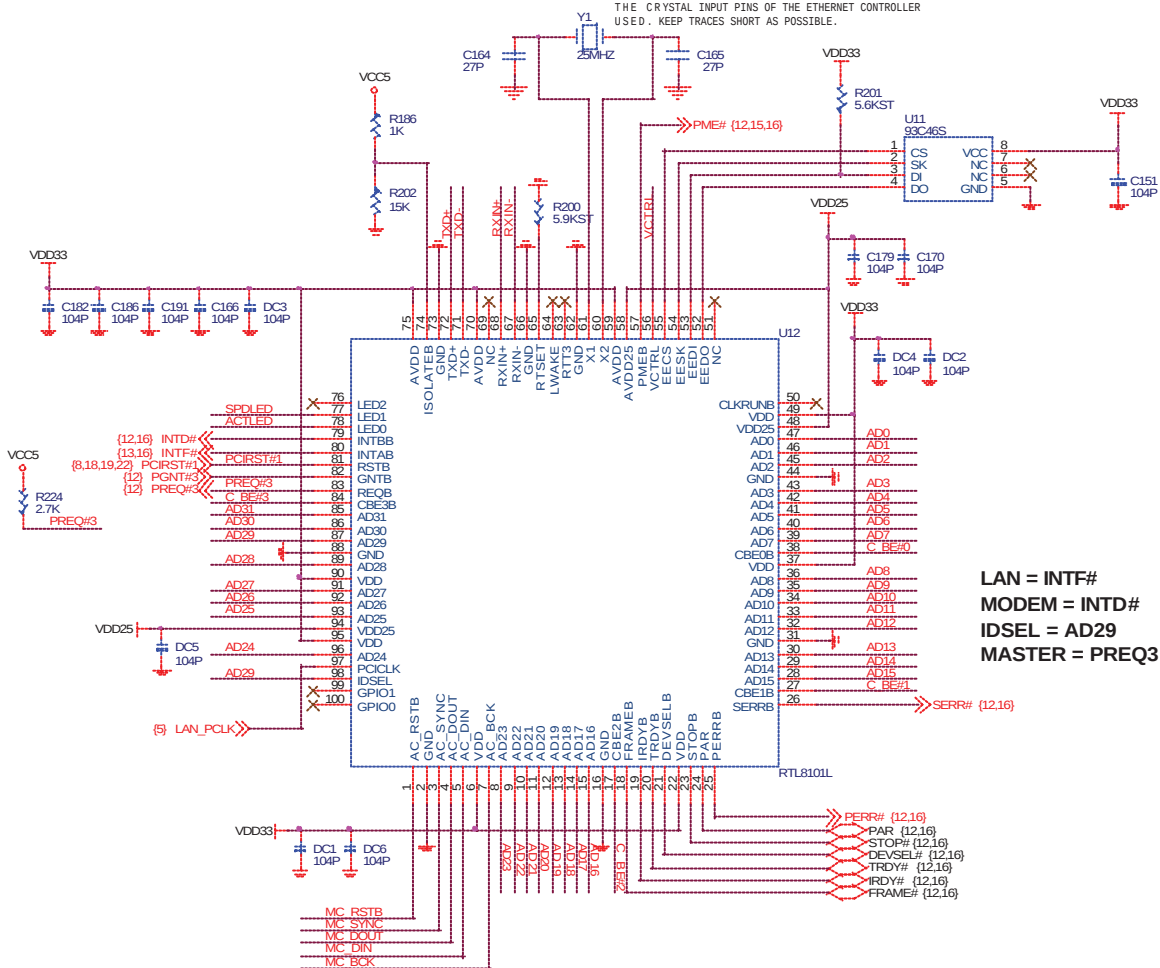


```
IDSEL = AD18
MASTER = PREQ2
INTC#
```

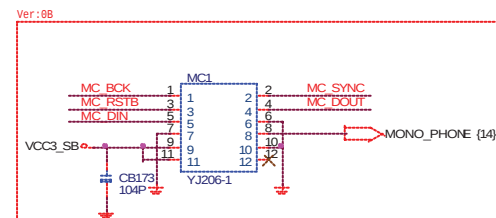
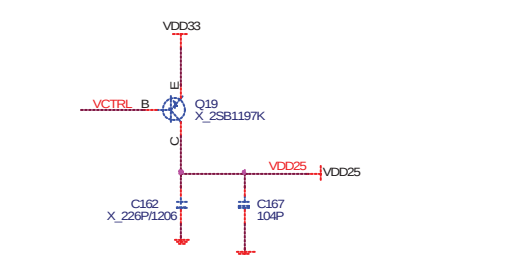
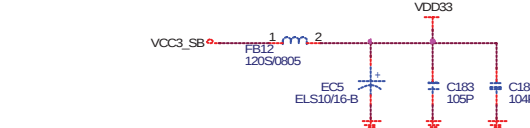
PCI SLOT DECOUPLING CAPACITORS



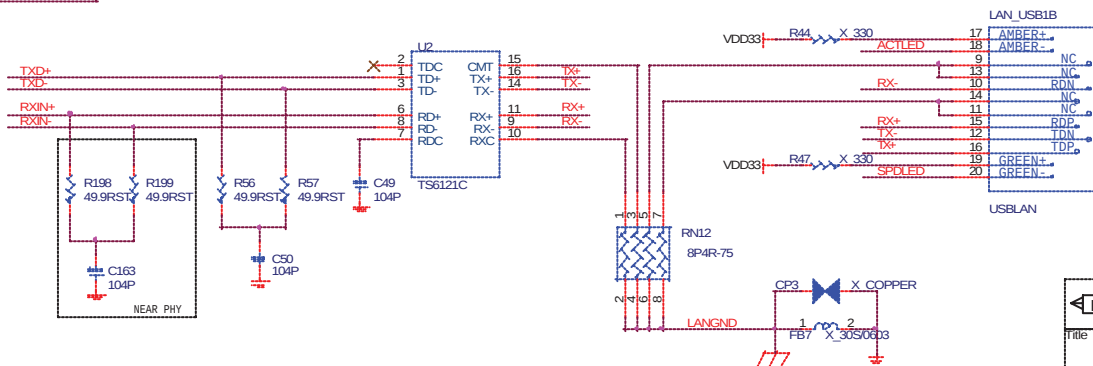
THIS DEVICE SHOULD BE PLACED AS CLOSE AS POSSIBLE TO THE CRYSTAL INPUT PINS OF THE ETHERNET CONTROLLER USED. KEEP TRACES SHORT AS POSSIBLE.



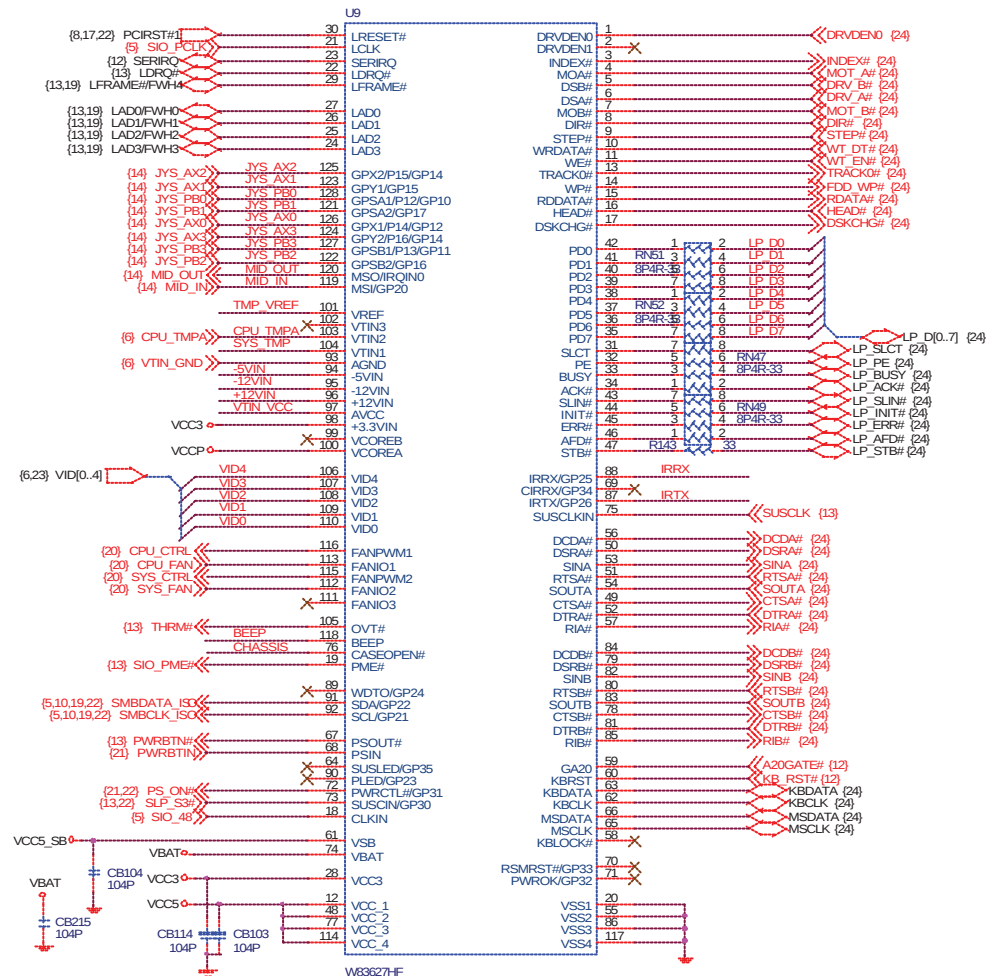
LAN = INTD#
MODEM = INTD#
IDSEL = AD29
MASTER = PREQ3



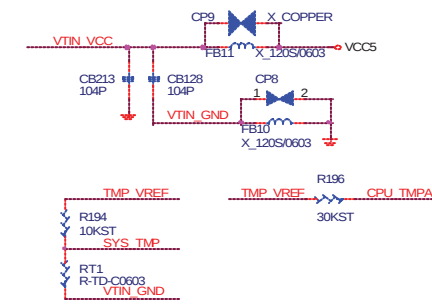
(12.16) AD[31:0] → AD31:0
(12.16) C_BE#[3:0] → C_BE#3:0



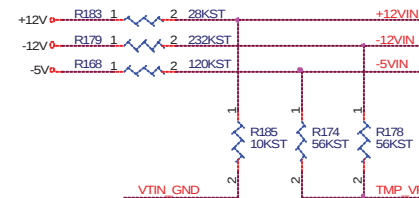
LPC SUPER I/O W83627HF



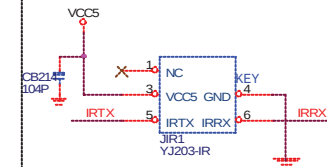
THERMAL RESISTOR BLOCK



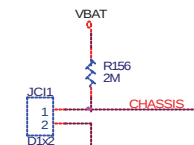
NOTE: LOCATE CLOSE STATUS PANEL



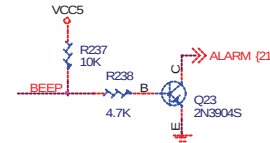
Intel Front IR Header



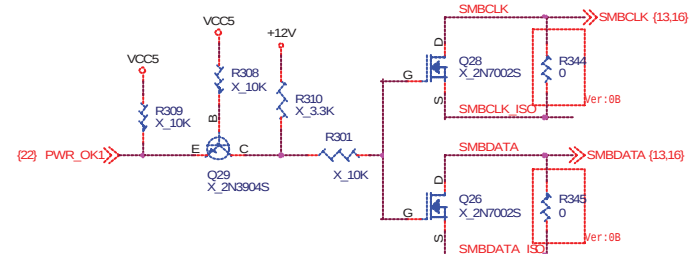
Chassis Intrusion Header



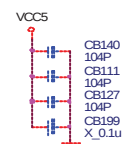
SPEAKER BLOCK



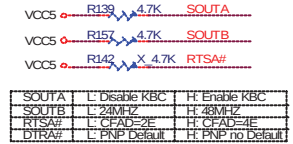
SMBus Isolation



LPC I/O DECOUPLING CAPACITORS

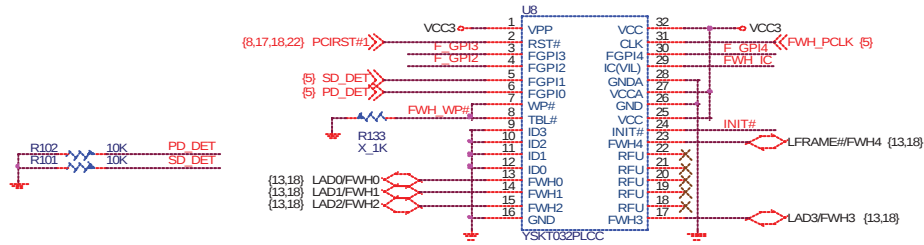


SUPER I/O STRAPPING RESISTOR

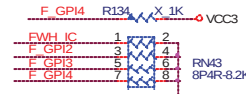


MICRO-STAR INT'L CO.,LTD.			
Title			
LPC IO & GAME PORT			
Size	Document Number	MS-6507E	
Date:	Monday, April 15, 2002	Sheet	18 of 31

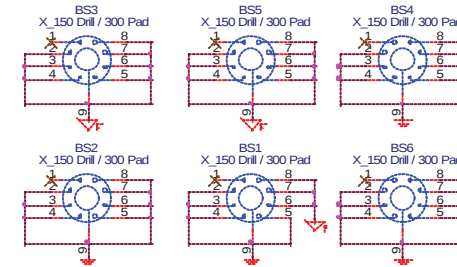
Firware Hub (FWH)



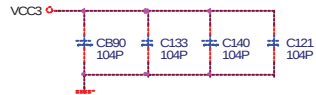
FWH RESISTORS



PCB Mounting Holes

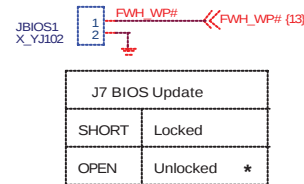


FWH DECOUPLING CAPACITORS



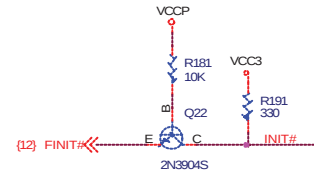
Place Cap. as Close to FWH< 350 mil

FWH write protect

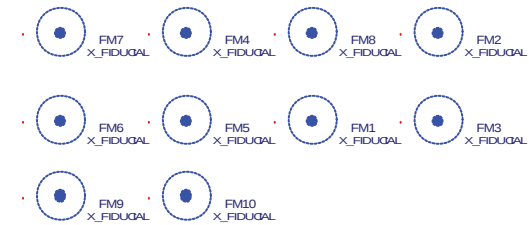


J7 BIOS Update		
SHORT	Locked	
OPEN	Unlocked	*

FWH INIT Signal Voltage Translation Block

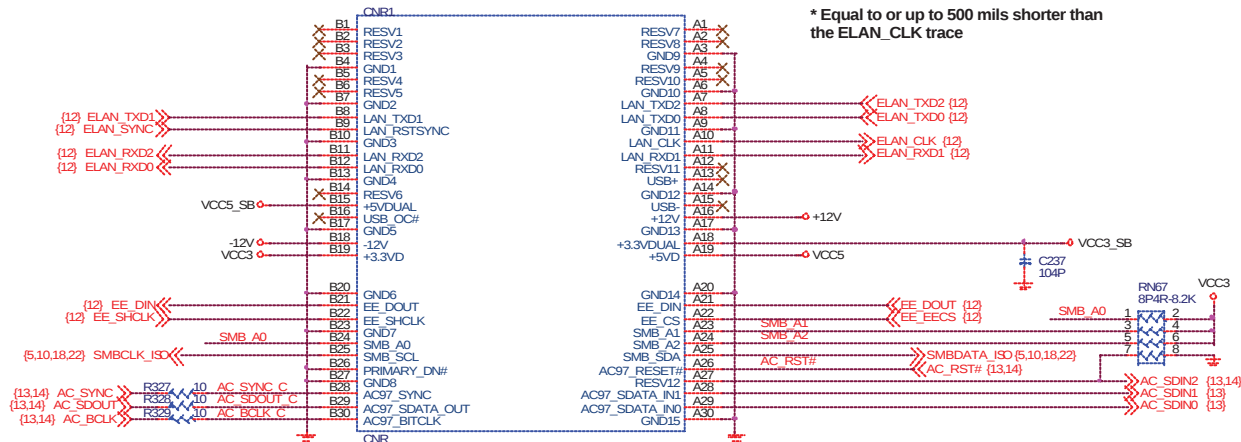


PCB Fiducials



CNR RISER

- * LAN Trace width : 5 mils
- * AC'97 Trace Spacing : 10 mils
- * Maximum trace length < 9.5"
- * Equal to or up to 500 mils shorter than the ELAN_CLK trace



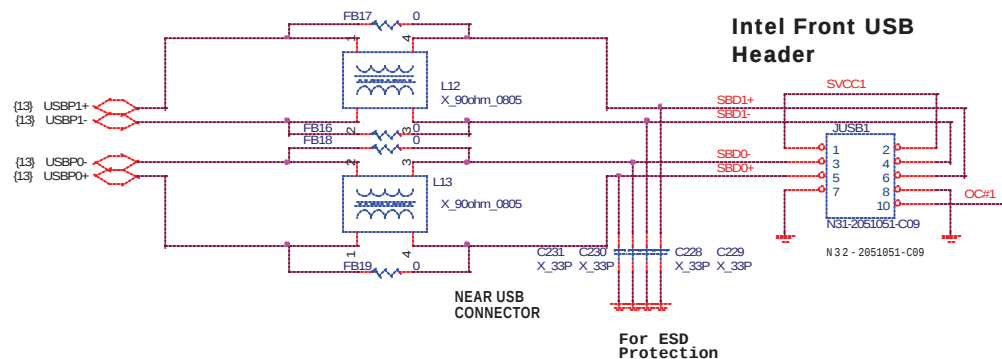
SIMULATION TRACE



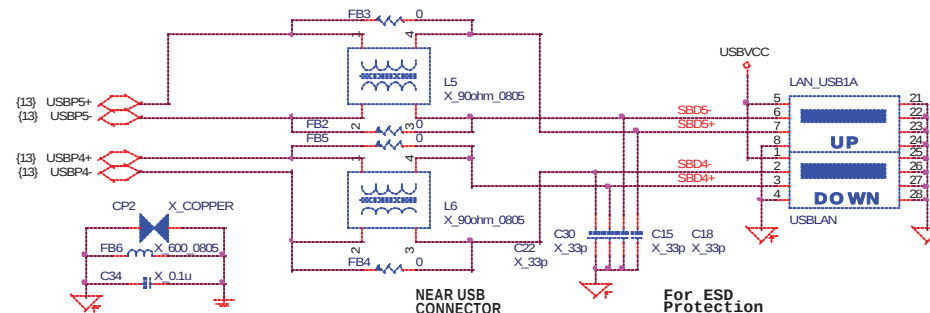
MICRO-STAR INT'L CO.,LTD.		
Title: FWH & CNR		
Size:	Document Number:	Rev: 1.0
MS-6507E		
Date: Monday, April 15, 2002	Sheet: 19	of 31

FRONT PANEL USB CONNECTOR FOR USB PORT 0,1

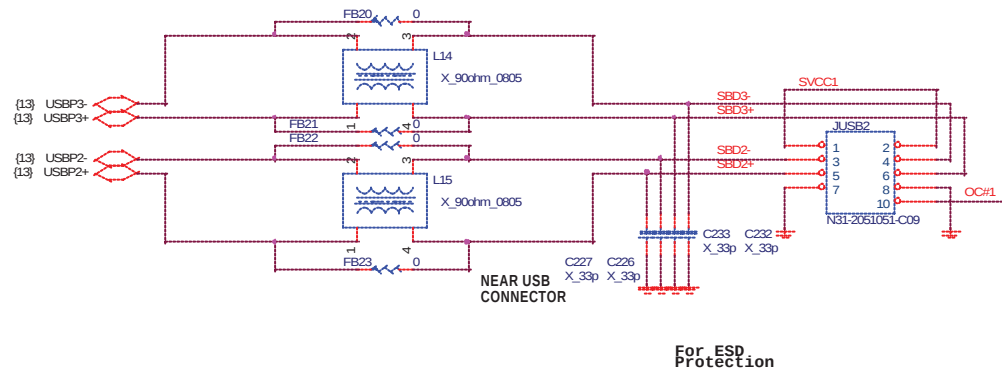
Intel Front USB Header



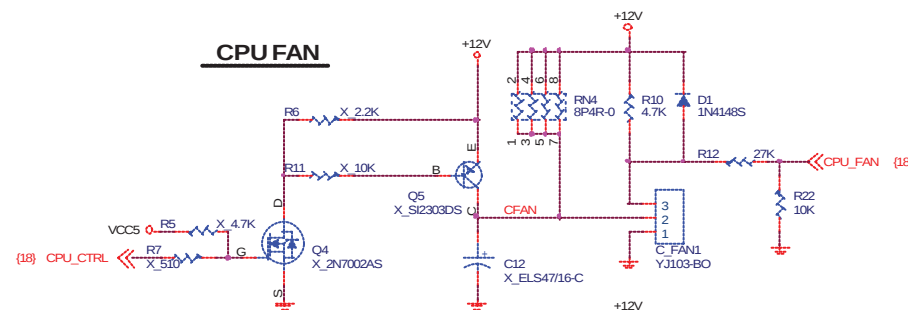
REAR PANEL USB CONNECTOR FOR USB PORT 4,5



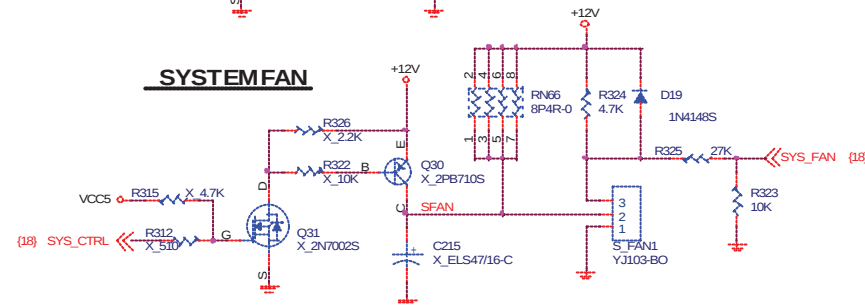
FRONT PANEL USB CONNECTOR FOR USB PORT 2,3



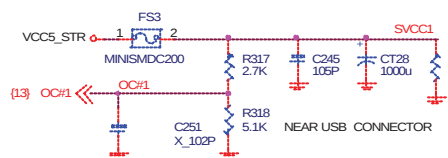
CPU FAN



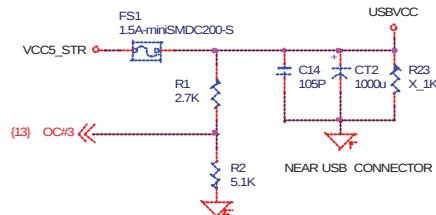
SYSTEM FAN



POWER CIRCUIT FOR USB PORT 0,1,2,3

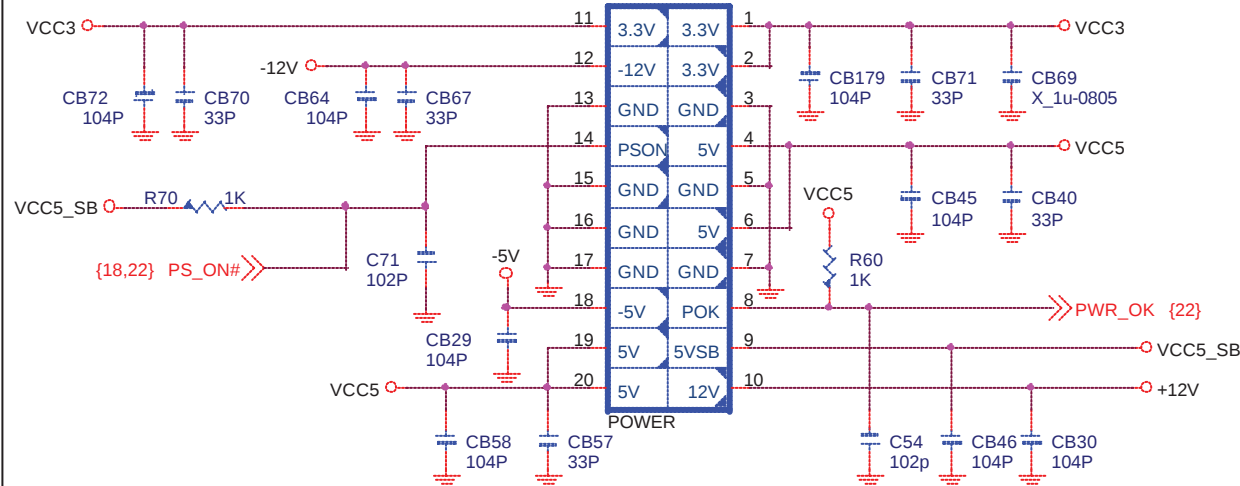


POWER CIRCUIT FOR USB PORT 4,5

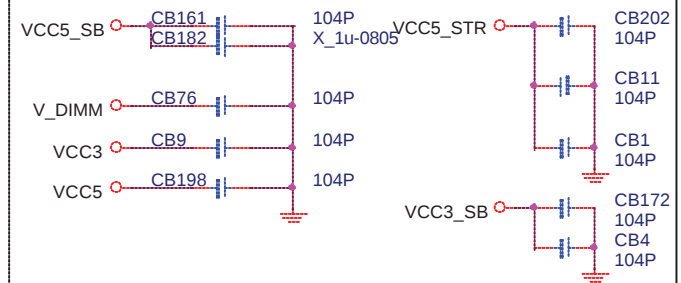


- * USB Trace width : 7.5 mils
- * USB Trace Spacing : 20 mils
- * Differential USB Signlas Trace, Spacing : 18 mils
- * USB Power Trace must be 40mils width

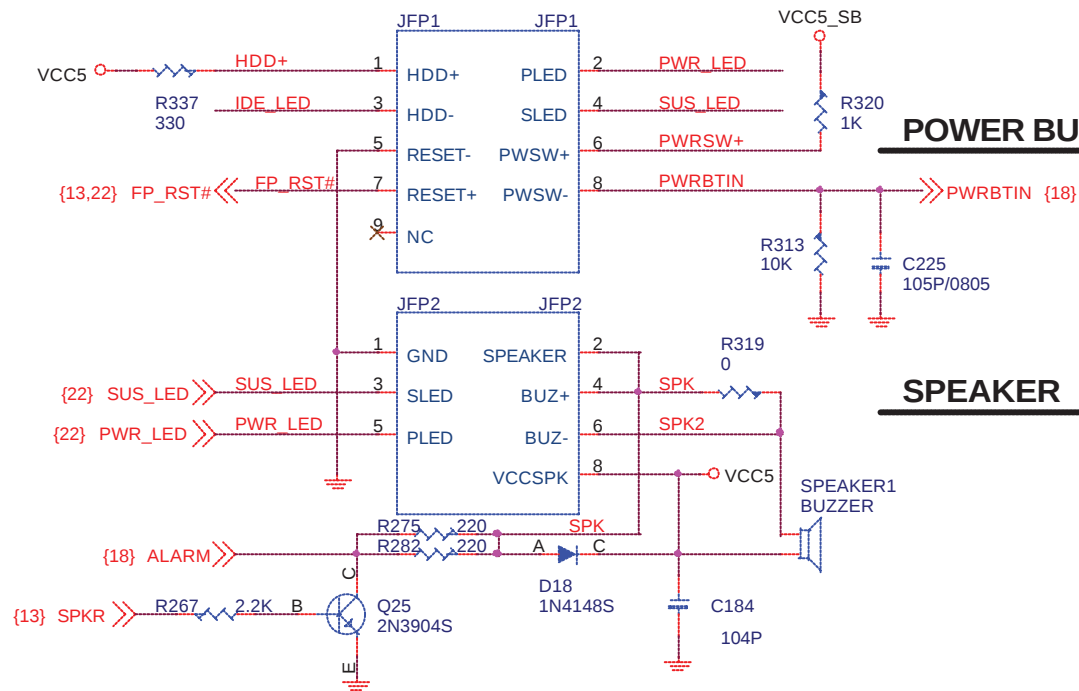
ATX CONNECTOR



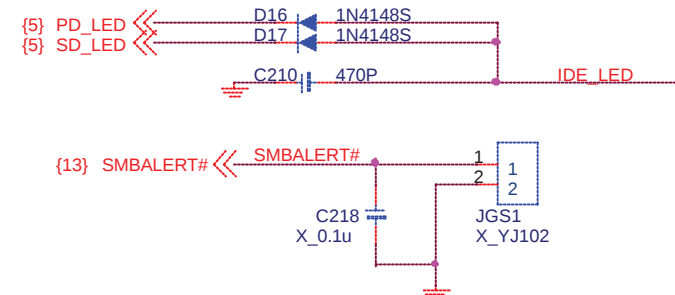
REGULATORS OUTPUT DECOUPLING CAPACITORS



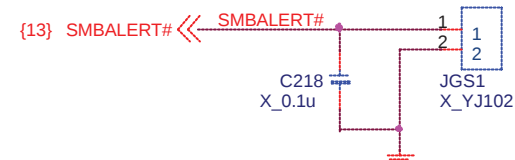
MSI/Intel Front Panel



POWER BUTTON

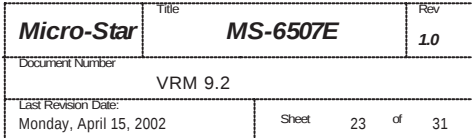


SPEAKER

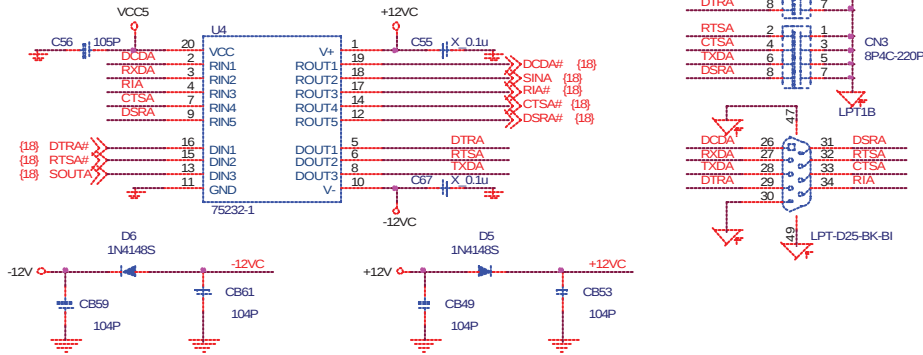


MICRO-STAR INT'L CO.,LTD.

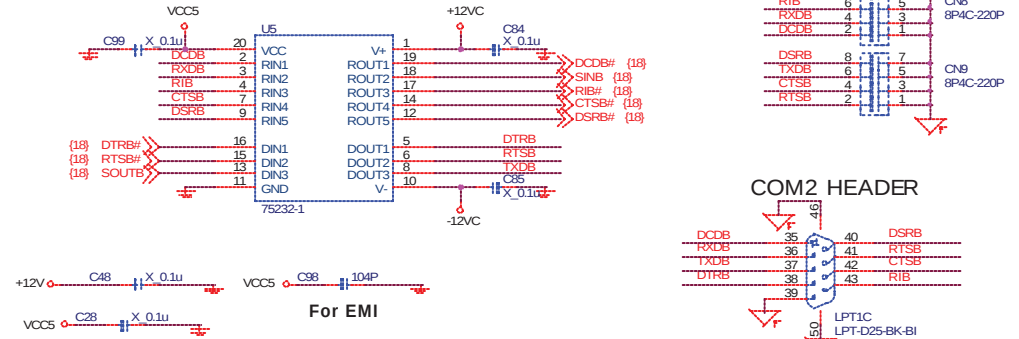
Title				
Front Panel & ATX Connector & FAN				
Size	Document Number			Rev
	MS-6507E			1.0
Date:	Monday, April 15, 2002		Sheet	21 of 31



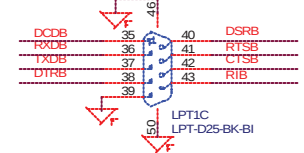
SERIAL PORT 1



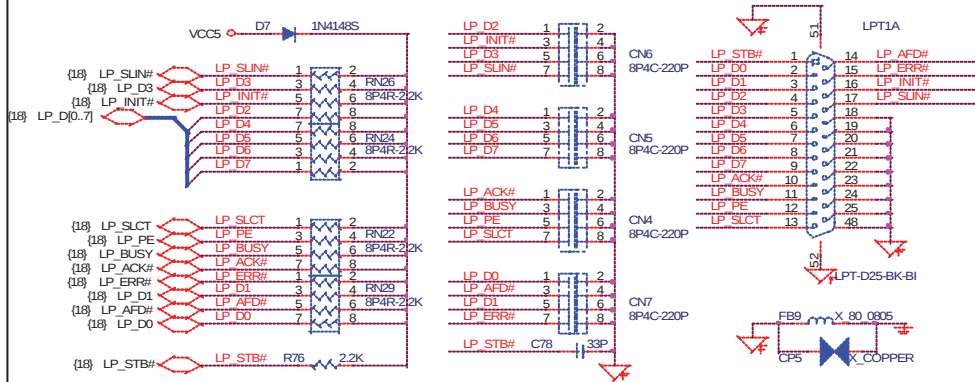
SERIAL PORT 2



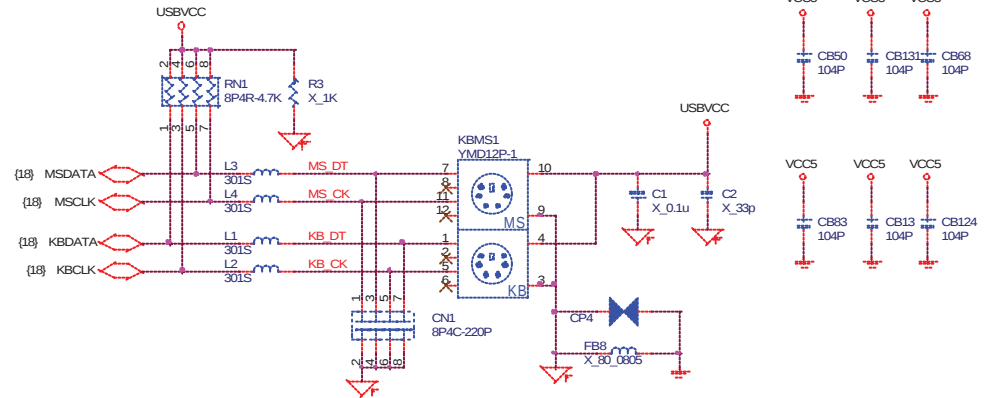
COM2 HEADER



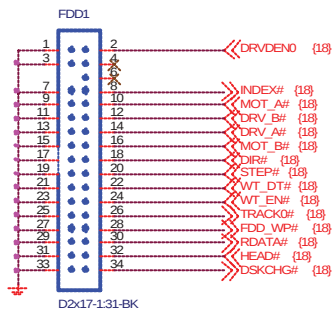
PARALLAL PORT



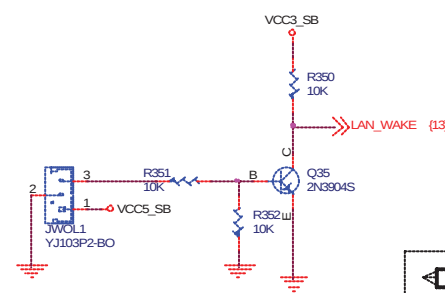
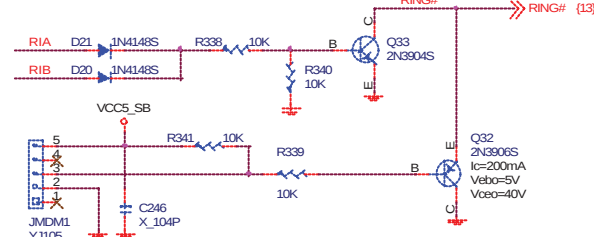
PS2 KEYBOARD & MOUSE CONNECTOR



FLOPPY CONNECTOR



Wake On Ring Header



0B Revision History (Changes from Rev 0A)

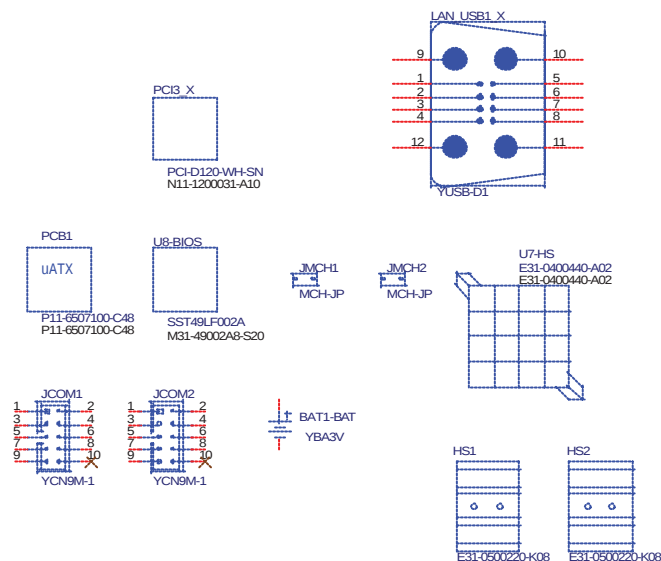
Sheet	Description
22	Change MS5 SLP_S3# Singnal source from PS_ON#.
18	Add two Resistor between Q26 and Q28 Drain and Source.
23	Change CP6 PCBFootPrint from JP to NC.
17	Swap MC1 Pin.1 & Pin.2
13	Change RSMRST# Pull-Up to VCC3_SB. Change THERMTRIP# Damp R217 be a VCCP Pull-Up Resistor. Change RTC Block Circuit.
12	Add Damping Resistor on PCIRST# for decrease PCIRST# Overshoot and UnderShoot on MS5.



Jumper Setting & Connector Setting

Jumper	Description
JAUDIO1	AUDIO FRONT PANEL HEADPHONE JACK HEADER
JBAT1	CLEAR CMOS
1-2	NORMAL (Default)
2-3	CLEAR CMOS

Connector	Description
U7	INTEL mPGA478-B CPU
PRIMAR1	Primary
SECON1	Secondary
DIMM1	SDRAM DIMM1
DIMM2	SDRAM DIMM2
AGP1	AGP Slot
PCI1	PCI Slot1
PCI2	PCI Slot2
PCI3	PCI Slot3(MEDION SPEC)
COM1	Serial Port
COM2	Serial Port
LPT1	Parallel Port
FDD1	Floppy
JMDM1	MODEM RING HEADER
KBMS1	PS/2 Keyboard and PS/2 mouse
C_FAN1	CPU FAN HEADER
LAN_USB1	LAN&USB REAR CONNECTOR
USB1	USB INTERNAL HEADER
USB2	USB INTERNAL HEADER
CONN1	ATX Power
JFP1	INTEL Front Panel
JFP2	MSI Front Panel
JPW1	ATX12V Power



Micro-Star	Title MS-6507	Rev 1.0
Document Number	JUMPER SETTING	
Last Revision Date: Monday, April 15, 2002	Sheet	26 of 31

Pentium 4 Processor /Northwood mPGA 478

Source Synchronous Signal Group and the Associated Strobes

Signals	Associated Strobe
REQ[4:0],A[16:3]#	ADSTB0#
A[31:17]#	ADSTB1#
D[15:0]#,DBI0#	DSTBP0#,DSTBN0#
D[31:16]#,DBI1#	DSTBP1#,DSTBN1#
D[47:32]#,DBI2#	DSTBP2#,DSTBN2#
D[63:48]#,DBI3#	DSTBP3#,DSTBN3#

Signals	Length	Inaccuracy
Data	2.0" to 10.0"	+/- 100 mil
Address	2.0" to 10.0"	+/- 200 mil
Strobe	2.0" to 10.0"	+/- 25 mil
Clock	2.0" to 10.0"	Don't need

* Delta=(CPU_pkglen.net-CPUpkglen.strobe)+(CS_pkglen.net-CS_pkglen.strobe)

Trace : 7 mil width 13mil space

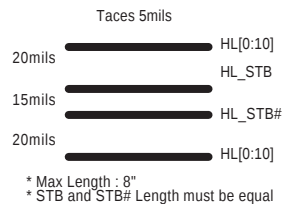
Miscellaneous Signals

AGP

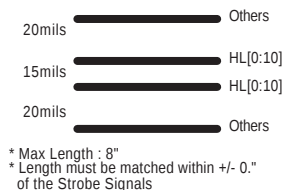
1X Timing group	2X/4X Timing group
	<u>SET#1</u>
AGPCLK	GAD[15..0]
PIPE#	GC_BE#[1..0]
RBF#	GAD_STB0
WBF#	GAD_STB0#
ST[2..0]	
GFRAME#	<u>SET#2</u>
GIRDY#	GAD[31..16]
GTRDY#	GC_BE#[3..2]
GSTOP#	GAD_STB1
GDEVSEL#	GAD_STB1#
GREQ#	
GGNT#	<u>SET#3</u>
GPAR	SBA[7..0]
	SB_STB
	SB_STB#

SIGNALS	Maximum Length	Width	Space	Dismatch Length	Relative to
1X Timing group	7.5"	5 mil	5 mil	X	X
2X/4X Timing group SET#1	7.25"	5 mil	20 mil	+/- 0.125"	GAD_STB0 GAD_STB0#
2X/4X Timing group SET#2	7.25"	5 mil	20 mil	+/- 0.125"	GAD_STB1 GAD_STB1#
2X/4X Timing group SET#3	7.25"	5 mil	20 mil	+/- 0.125"	SB_STB SB_STB#
2X/4X Timing group SET#1	6"	5 mil	15 mil	+/- 0.25"	GAD_STB0 GAD_STB0#
2X/4X Timing group SET#2	6"	5 mil	15 mil	+/- 0.25"	GAD_STB1 GAD_STB1#
2X/4X Timing group SET#3	6"	5 mil	15 mil	+/- 0.25"	SB_STB SB_STB#

HL_STB/HL_STB#



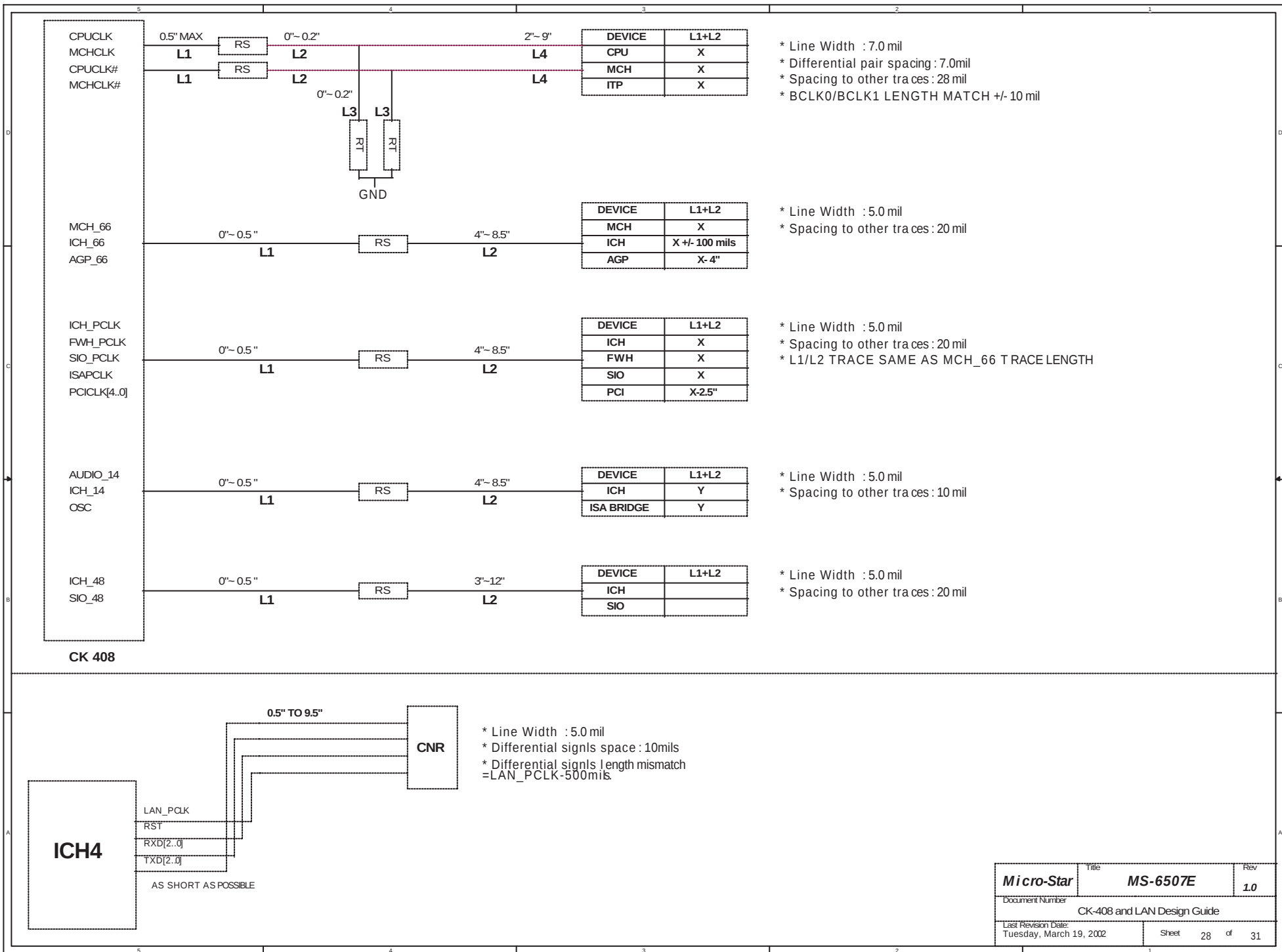
HL[10..0]



USB

- * USB Trace width : 7.5 mils
- * Differential USB Signlas Trace Spacing : 7.5mils
- * USB Trace Spacing with other signals:20 mils
- * USB Power Trace must be 40mils width

Micro-Star	Title MS-6507E	Rev 1.0
Document Number		
Revision History - 1		
Last Revision Date: Tuesday, March 19, 2002	Sheet 27	of 31



SDRAM Routing Guidelines

5.Feedback - RDCLK0,RDCLKIN routing rule

2 or 3 DIMM feedback layout guideline

Signal	Length	Width	Trace Spacing
Trace L	50 mils	7 mil	5 mil



DDR-SDRAM Routing Guidelines

1.DDR bus reference plane stack-up

PCB Layer	Description
Layer 1	Signal
Layer 2	Ground Flood
Layer 3	Ground
Layer 4	Power / Signal

*All the memory bus signals must be referenced to GND

2.DDR signal groups

Group	Signals
Data	SDQ[63:0], SCB[7:0], SDQS[8:0]
Command	SMA[12:0], SBS[1:0], SRAS#, SCAS#, SWE#
Control	SCKE[3:0], SCs#[3:0]
Clock	SCK[5:0], SCK#[5:0]
Feedback	RCVENOUT#, RCVENIN#

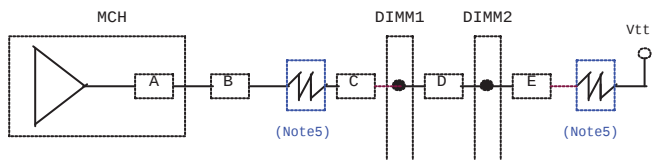
SDQS[8:0] were Data Strobes.

3. SDQ[63:0], SCB[7:0], SDQS[8:], SCK/SCK#[5:0] routing rule

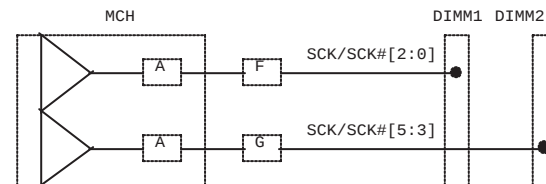
Signal	Length A	Length B	Length C	Length D	Length E	Width	Spacing	Routing Layer
SDQ[63:0] SCB[7:0] SDQS[8:0] (Note1)	Package length	2.0" - 5.0"	Max = 0.5"	0.3' - 0.5"	0.1" - 0.8"	5 mil	(Note2)	Top
	DIMM 1 = A + B + C = X							
	DIMM 2 = A + B + C + D = X + D							
SCK/SCK#[2:0]	Package length	B+C+2" <= Length F <= B+C+1"	None	None	None	5 mil	(Note4)	Bottom
		2.0" - 6.5"						
	DIMM 1 = A + F = X + 1" to X + 2"							
SCK/SCK#[5:3] (Note3)	Package length	B+C+D+2" <= Length G <= B+C+D+1"				5 mil	(Note4)	Bottom
		2.5" - 7.0"						
	DIMM 2 = A + G = X + D + 1" to X + D + 2"							

* Package length see Table - 4

SDQ[63:0], SCB[7:0], SDQS[8:] layout guideline



SCK[5:0] layout guideline



Note1:Each data and strobe signal group must be length matching +/- 25 mils

SDQS[X] = +/- 25 mils SDQ[X]/SCB[X] group length

Signals	Associated Strobe
SDQ[7:0]	SDQ0
SDQ[15:8]	SDQ1
SDQ[23:16]	SDQ2
SDQ[31:17]	SDQ3
SDQ[39:32]	SDQ4
SDQ[47:40]	SDQ5
SDQ[55:48]	SDQ6
SDQ[63:56]	SDQ7
SCB[7:0]	SDQ8

Note2:Trace spacing normally = 12 mils and through between DIMM 2 pin = 7 mils, but breakout form MCH ball = 5 mils width with 7mils spacing for a max of 350mils

Note3:

* SCK[X] length = SCK#[X] length

* SCK/SCK#[2:0] routed to DIMM 0 are equal in length, and SCK/SCK#[5:3] routed to DIMM 1 are equal in length

Note4:

* Between the pair differential clock 2 signal trace spacing = 7 mils

* Differential Trace with 2.5V copper flood spacing = 10 mils minimum

* Serpentine spacing = 20 mils minimum

* Differential signals breakout form MCH = 5 mil width with 7 mil differential spacing and 7 mil isolation spacing from another signal for a max of 350 mils

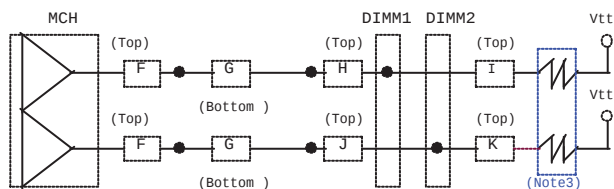
Note5:Data group signal can NOT placed within the same RPACK's(series and parallel resistor packs) as the command or control group signal

Micro-Star	Title MS-6507E	Rev 1.0
Document Number	DDR Layout Guideline1	
Last Revision Date: Tuesday, March 19, 2002	Sheet 29	of 31

DDR-SDRAM Routing Guidelines

4. SCKE[3:0], SCS#[3:0] routing rule

DIMM 0					
Signal	Length F	Length G	Length H	Length I	Width
SCS#[1:0] SCKE[1:0] (Note1)	Max = 40 mils	2.0" - 3.5"	Max = 500 mils (Note2)	0.4" - 1.3"	5 mils
Total lenght	DIMM0 SCK/SCK#[2:0] length = X" DIMM0 SCS#/SCKE length = F + G + H = X" - 1"				
DIMM 1					
Signal	Length F	Length G	Length J	Length K	Width
SCS#[3:2] SCKE[3:2] (Note1)	Max = 40 mils	2.0" - 3.5"	Max = 1" (Note2)	0.1" - 0.8"	5 mils
Total lenght	DIMM1 SCK/SCK#[5:3] length = Y" DIMM1 SCS#/SCKE length = F + G + J = Y" - 1"				



Note1:

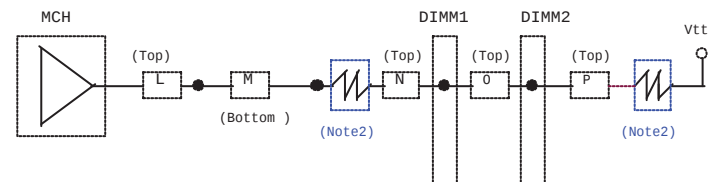
- *Trace spacing normally = 12 mils and through between DIMM 2 pin or DIMM to Rtt = 7 mils, but breakout form MCH ball = 5 mils width with 7mils spacing for a max of 350mils
- *Trace with 2.5V copper flood spacing = 7 mils minimum
- *Isolation spacing form another group signal spacing = 20 mils minimum
- *Control signals breakout form MCH = 5 mil width with 7 mil spacing for a max of 350 mils

Note2: This purpose prevent break form DIMM0 bottom size 2.5V copper flood to MCH power plane

Note3: Control group signal can NOT placed within the same parallel resistor packs as the command or data group signal

5. SMA[12:0], SBS[1:0], SRAS#, SCAS# routing rule

Signal	Length L	Length M	Length N	Length O	Length P	Width
SMA[12:0] SBS[1:0] SRAS# SCAS# (Note1)	Max = 40 mils	2.0" - 3.5"	Max = 500 mils	0.3" - 0.5"	0.1" - 0.8"	5 mils
DIMM 0 Total lenght	DIMM0 SCK/SCK#[2:0] length = X" Command signal length = L + M + N = X" - 1"					
DIMM 1 Total lenght	DIMM0 SCK/SCK#[5:3] length = Y" Command signal length = L + M + N + O = Y" - 1"					



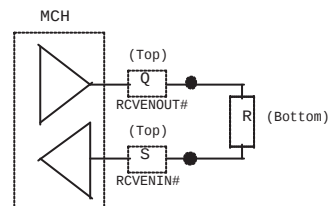
Note1:

- *Trace spacing normally = 12 mils and through between DIMM 2 pin or DIMM to Rtt = 7 mils, but breakout form MCH ball = 5 mils width with 7mils spacing for a max of 350mils
- *Trace with 2.5V copper flood spacing = 7 mils minimum
- *Isolation spacing form another group signal spacing = 20 mils minimum
- *Command signals breakout form MCH = 5 mil width with 7 mil spacing for a max of 350 mils

Note2: Command group signal can NOT placed within the same RPACK's (series and parallel resistor packs) as the data or control group signal

5. Feedback - RCVENOUT#, RCVENIN# routing rule

Signal	Length Q	Length R	Length S	Width
RCVENOUT# RCVENIN# (Note1)	40 mils	Equal 1"	40 mils	5 mils
Total Length	Q + R + S = 1080 mils			



Note1:

- *Trace spacing = 12 mils
- *Trace with 2.5V copper flood spacing = 7 mils minimum
- *Isolation spacing form another group signal spacing = 10 mils minimum
- *Command signals breakout form MCH = 5 mil width with 7 mil spacing for a max of 350 mils

Table - 4

DDR Data Signals(1)		
Signal	MCH ball	Package length(in)
SDQ0	G28	0.716
SDQ1	F27	0.699
SDQ2	C28	0.874
SDQ3	E28	0.754
SDQ4	H25	0.532
SDQ5	G27	0.666
SDQ6	F25	0.592
SDQ7	B28	0.892
SDQ8	E27	0.797
SDQ9	C27	0.833
SDQ10	B25	0.812
SDQ11	C25	0.753
SDQ12	B27	0.886
SDQ13	D27	0.867
SDQ14	D26	0.773
SDQ15	E25	0.645
SDQ16	D24	0.722
SDQ17	E23	0.602
SDQ18	C22	0.699
SDQ19	E21	0.566
SDQ20	C24	0.785
SDQ21	B23	0.781
SDQ22	D22	0.640
SDQ23	B21	0.711
SDQ24	C21	0.627
SDQ25	D20	0.555
SDQ26	C19	0.587
SDQ27	D18	0.522
SDQ28	C20	0.615
SDQ29	E19	0.487
SDQ30	C18	0.579
SDQ31	E17	0.521

DDR Data Signals(2)		
Signal	MCH ball	Package length(in)
SDQ32	E13	0.432
SDQ33	C12	0.543
SDQ34	B11	0.596
SDQ35	C10	0.590
SDQ36	B13	0.639
SDQ37	C13	0.552
SDQ38	C11	0.588
SDQ39	D10	0.626
SDQ40	E10	0.533
SDQ41	C9	0.605
SDQ42	D8	0.587
SDQ43	E8	0.522
SDQ44	E11	0.523
SDQ45	B9	0.715
SDQ46	B7	0.706
SDQ47	C7	0.643
SDQ48	C6	0.700
SDQ49	D6	0.664
SDQ50	D4	0.760
SDQ51	B3	0.922
SDQ52	E6	0.640
SDQ53	B5	0.846
SDQ54	C4	0.810
SDQ55	E5	0.670
SDQ56	C3	0.859
SDQ57	D3	0.811
SDQ58	F4	0.723
SDQ59	F3	0.814
SDQ60	B2	0.949
SDQ61	C2	0.893
SDQ62	E2	0.865
SDQ63	G5	0.689

DDR ECC Signals		
Signal	MCH ball	Package length(in)
SCB0	C16	0.570
SCB1	D16	0.526
SCB2	B15	0.623
SCB3	C14	0.533
SCB4	B17	0.621
SCB5	C17	0.583
SCB6	C15	0.540
SCB7	D14	0.503

DDR Data Strobe Signals		
Signal	MCH ball	Package length(in)
SDQS0	F26	0.651
SDQS1	C26	0.775
SDQS2	C23	0.738
SDQS3	B19	0.636
SDQS4	D12	0.493
SDQS5	C8	0.596
SDQS6	C5	0.776
SDQS7	E3	0.821
SDQS8	E15	0.520

DDR Clock Signals		
Signal	MCH ball	Package length(in)
SCK0	E14	0.453
SCK#0	F15	0.432
SCK1	J24	0.454
SCK#1	G25	0.587
SCK2	G6	0.551
SCK#2	G7	0.543
SCK3	G15	0.371
SCK#3	G14	0.349
SCK4	E24	0.610
SCK#4	G24	0.548
SCK5	H5	0.589
SCK#5	F5	0.693

Micro-Star	Title	MS-6507E	Rev
			1.0
	Document Number		
DDR Layout Guideline3			
Last Revision Date: Tuesday, March 19, 2002		Sheet	31 of 31